



## Material declaration form

General Information			
IPC	1752	Version	2
Form type*	Distribute		
Sectionals*	Material information	Subsectionals*	A-D
	Manufacturing information		*: Required Field

Supplier Information			
Company name*	STMicroelectronics	Response Date*	2025-05-20
Contact name*	Refer to Supplier Comment section		Refer to Supplier Comment section
Contact phone*	Refer to Supplier Comment section	Contact email*	Refer to Supplier Comment section
Authorized representative*	Antonella Lanzafame	Representative title	APMSMaterial Declaration champion
Representative phone*	Refer to Supplier Comment section	Representative email*	Refer to Supplier Comment section
Supplier comment	Online Technical Support - STMicroelectronics : <a href="http://www.st.com/web/en/support/support.html">http://www.st.com/web/en/support/support.html</a>		

**Uncertainty statement**

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**Legal statement**

Supplier acceptance\* true Legal declaration\* Standard

Supplier certifies that it gathered the provided information and such information is true and correct to the best of its knowledge and belief, as of the date that Supplier completes this form. Supplier acknowledges that Company will rely on this certification in determining the compliance of its products. Company acknowledges that Supplier may have relied on information provided by others in completing this form, and that Supplier may not have independently verified such information. However, in situations where Supplier has not independently verified information provided by others, Supplier agrees that, at a minimum, its suppliers have provided certifications regarding their contributions to the part(s), and those certifications are at least as comprehensive as the certification in this paragraph. If the Company and the Supplier enter into a written agreement with respect to the identified part(s), the terms and conditions of that agreement, including any warranty rights and/or remedies provided as part of that agreement, will be the sole and exclusive source of the Supplier's liability and the Company's remedies for issues that arise regarding information the Supplier provides in this form.

Product				
Mfr item number	Mfr item name	Version	Manufacturing site	date
SCT040W120G3AG	T36J*BR19GV2	A	SH1A	2025-05-20
	Amount	Unit of measure	Unit type	ST ECOPACK grade
	4500	mg	Each	ECOPACK® 2
<b>Identity</b>	<b>Authority</b>			
Comment	0			

Manufacturing Information				
J-STD-020 MSL rating	Classification temperature	Number of reflow cycles		
Not Applicable	Not Applicable	,		
Bulk solder termination	Terminal plating	Terminal base alloy	Comment	
Not Applicable	Tin (Sn), matte, annealed	Copper Alloy	0	

Package designator	Package size	Number of instances	Shape	
SIP	19.85x15.45	3	Through-hole	
Comment				
Comment	B06J HIP-247 IN LINE HEAT SINK 2MM			

QueryList : RoHS Directive 2011/65/EU- 8 June 2011 – Annex II amended by Delegated Directive 2015/863 - 31 March 2015		Response
1 - Product(s) meets EU RoHS requirement without any exemptions		false
2 - Product(s) meets EU RoHS requirements except lead in solder and this usage may qualify under the lead in solder '7b' exemption (other selected exemptions may apply)		false
3 - Product(s) meets EU RoHS requirements by application of the selected exemption(s)		true
4 - Product(s) does not meet EU RoHS requirements and is not under exemptions		false
Exemption Id.	Description	
7a	Lead in high melting temperature type solders (i.e. lead- based alloys containing 85 % by weight or more lead)	

QueryList : ELV directive : 2000/53/EC amended 2020/363_March 2020		Response
1 - Product(s) meets EU ELV requirements without any exemptions		false
2 - Product(s) meets EU RoHS requirements by application of the selected exemption(s)		true
Exemption Id.	Description	
8(e)	8(e) - Lead in high melting temperature type solders (i.e. lead-based alloys containing 85 % by weight or more lead)	

QueryList : California Prop65 list, dated 3rd January 2025				Response
1 - The product does not contain identified substance from California Prop 65 List, no exposure to consumers is foreseen				false
2 - The product is containing below substance(s) from California Prop 65 List, no exposure to consumers is foreseen				true
Substance	amount in product (mg)	Application	ppm in product	
Nickel	11.141	die + leadframe	2476	
Lead	3.333	solder	741	

QueryList :Customer		Response
QUERY		Response

QueryList : Chinese RoHS , references : SJT 11364 – 2014 and GBT 26572 – 2014					Response
QUERY					Response
1 - Product(s) requires marking for the presence of restricted substances and must be marked with an Environmental Protection Use Period under China's Measures for Administration of the control of pollution by Electronic Information Products					true
2 - Product(s) is eligible for marking with the e code under China's Measures for Administration of the control of pollution by Electronic Information Products					false
Hazardous substance					
Lead (Pb)	Cadmium (Cd)	Mercury (Hg)	Hexavalent Chromium (Cr VI)	PBB & PBDE	
X	O	O	O	O	

QueryList : REACH-21st January 2025					Response
1 - Product(s) does not contain REACH Substances Of Very High Concern above the limits per the definition within REACH					true
CategoryLevel_Name	CategoryLevel_Threshold	amount in product (mg)	Application	ppm in product	
2 - Product(s) does not contain REACH Substances Of Very High Concern in any Embedded article nor Homogeneous Material above the limits per the definition within REACH					false
CategoryLevel_Name	CategoryLevel_Threshold	Amount in embedded article / Homogeneous material (mg)	Application - article / Homogeneous material	ppm in article /Homogeneous material	
Lead	1000 ppm	3.333	Soft solder	955014	



QueryList : Responsible metals sourcing	Response
The component is containing at least one of the following metals : Cobalt , Gold , Tantalum , Tin , Tungsten.	true
The following metals are present is the component :	<b>Tin,</b>

QueryList : Korea Chemical Control Act_ 27 Dec 2017 update	Response
The Product does contain at least one of the substances listed in Chemical Control Act	false

QueryList : China GB 33372-2020 Limit standard for volatile organic compounds content in adhesives - 4 March 2020 application date 1st December 2020	Response
The product contains adhesives identified under GB 33372	false

QueryList:Stockholm Convention Persistent Organic Pollutants (POP)	Response
Product is compliant with Annex A, B and C of Stockholm Convention Persistent Organic Pollutants	true

QueryList: EU Ship Recycling Regulation No. 1257/2013	Response
Product contains hazardous materials listed in Annex II of EU Ship Recycling Regulation No.1257/2013 and 2009/16/EC Directive	True
The material present in the product is:	Lead

PFAS/PTFE Declaration	Response
<b>QUERY</b>	<b>Response</b>
The product is containing fluorinated substance.	False
<b>Substance Name, CAS</b>	
Polytetrafluoroethylene, CAS 9002-84-0	False
Thiophenium CAS, 209482-18-8	False
Triphenylsulfonium nonaflate, CAS 144317-44-2	False
Trifluoroacetic anhydrid,e CAS 407-25-0	False

BPA Declaration	Response
Product does not contain Bisphenol A (Isopropylidenediphenol)	True

Montreal Protocol	Response
Product does not contain Ozone Depleting Substances based on Annex I to Annex VII of EU REGULATION (EC) No 1005/2009	True

Environmental Protection Agency:Toxic Substances Control Act (TSCA). Section 6(h)	Response
Product does not contain Phenol, isopropylated, phosphate (3:1)	True



Material Composition Declaration : note : Substance present with less 0.001mg will not be declared in this document						Mfr Item Name	T36J*BR19GV2		4500.0000		7000003.0	999998.0
Homogeneous material	Material group	Mass	Unit of measure	Level	Substance category	Substance	CAS	Exempt	Mass	Unit of measure	Concentration in homogeneous material (ppm)	Concentration in product (ppm)
Die	M-011 Other inorganic materials	5.888	mg	supplier	die	Silicon(Si)	7440-21-3		0.024	mg	4076	5
	M-011 Other inorganic materials			California 65	die	Silicium carbide	409-21-2		5.516	mg	936821	1226
				supplier	metallisation	Aluminium(Al)	7429-90-5		0.101	mg	17154	22
				supplier	metallisation	Copper(Cu)	7440-50-8		0.014	mg	2378	3
				supplier	metallisation	Nickel(Ni)	7440-02-0		0.087	mg	14776	19
				supplier	metallisation	Silver(Ag)	7440-22-4		0.089	mg	15115	20
				supplier	metallisation	Titanium(Ti)	7440-32-6		0.011	mg	1868	2
				supplier	metallisation	Vanadium(V)	7440-62-2		0.003	mg	510	1
				supplier	Passivation	Silicon nitride(Si)	12033-89-5		0.016	mg	2717	4
				supplier	passivation	Silicon oxide	7631-86-9		0.027	mg	4586	6
Leadframe	M-004 Copper and its alloys	4381.758	mg	supplier	alloy	Copper(Cu)	7440-50-8		4365.022	mg	996181	970005
				supplier	alloy	Iron phosphide	26509-33-8		3.671	mg	838	816
				supplier	alloy	Iron(Fe)	7439-89-6		2.011	mg	459	447
				supplier	metallization	Nickel(Ni)	7440-02-0		11.054	mg	2523	2456
Soft solder	Solder	3.490	mg	SVHC	solder	Lead(Pb)	7439-92-1	7a-Lead in high melting temperat	3.333	mg	955014	741
				supplier	solder	Silver(Ag)	7440-22-4		0.087	mg	24928	19
				supplier	solder	Tin(Sn)	7440-31-5		0.070	mg	20057	16
Bonding wires	M-003 Aluminum and its alloys	0.188	mg	supplier	wire	Aluminium (Al)	7429-90-5		0.187	mg	994681	42
	0			supplier	wire	Magnesium (Mg)	7439-95-4		0.001	mg	5319	0
Bonding wires 2	M-003 Aluminum and its alloys	1.475	mg	supplier	wire	Aluminium (Al)	7429-90-5		1.475	mg	1000000	328
Encapsulation	M-011 Other inorganic materials	101.004	mg	supplier	mold compound	Epoxy resin	120206-26-0		5.050	mg	49998	1122
				supplier	mold compound	Phenol Resin	106466-55-1		1.010	mg	10000	224
				supplier	mold compound	Silica(Amorphous)	60676-86-0		70.703	mg	700002	15712
				supplier	mold compound	Silica(Amorphous)	7631-86-9		20.201	mg	200002	4489
				supplier	mold compound	Silane Compound	919-30-2		1.010	mg	10000	224
				supplier	mold compound	Catalyst	502157-74-6		1.010	mg	10000	224
				supplier	mold compound	2,3-Naphthalene	92-44-4		1.010	mg	10000	224
	supplier	mold compound	Carbon black	1333-86-4		1.010	mg	10000	224			
Connections coating	Solder	6.197	mg	supplier	solder alloy	Tin(Sn)	7440-31-5		6.197	mg	1000000	1377